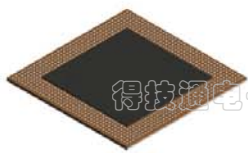


IC 测试座 & 老化座

IC Test and Burn-in Sockets



BGA  
(Ball Grid Array)



DIP  
(Dual In-Line Package)



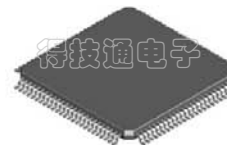
MLF  
(Micro Lead Frame)



PLCC  
(Plastic Leaded Chip Carrier)



QFN  
(Quad Flat No-Lead Package)



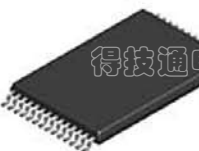
QFP  
(Quad Flatpack Package)



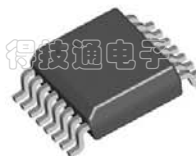
SOIC  
(Small Out-Line Integrated Circuit)



SOP  
(Small Out-Line Package)



TSOP  
(Thin Small Out-Line Package)



SSOP  
(Shrink Small Out-Line Package)

代理名牌测试座、老化座

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